P-channel enhancement mode vertical D-MOS transistor

BSP92

FEATURES

- Low threshold voltage $V_{GS(th)}$
- Direct interface to C-MOS, TTL, etc.
- High-speed switching
- No secondary breakdown.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
$-V_{DS}$	drain-source voltage	240	V
$-I_D$	DC drain current	180	mA
$R_{DS(on)}$	drain-source on-resistance	20	Ω
$-V_{GS(th)}$	gate-source threshold voltage	1.8	V

DESCRIPTION

P-channel enhancement mode vertical D-MOS transistor in a SOT223 envelope, intended for use as a surface-mounted device in line current interruptor in telephone sets and for application in relay, high speed and line transformer drivers.

PINNING

PIN	DESCRIPTION
1	gate
2	drain
3	source
4	drain

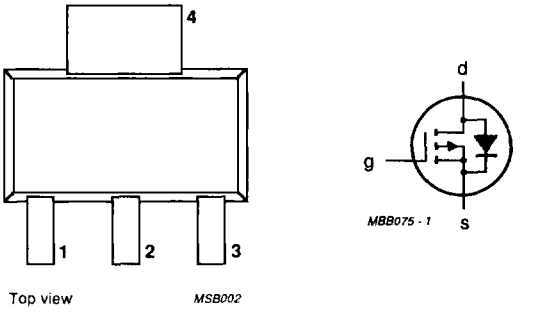

Fig.1 Simplified outline (SOT223) and symbol.

LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$-V_{DS}$	drain-source voltage		–	240	V
$\pm V_{GSO}$	gate-source voltage	open drain	–	20	V
$-I_D$	DC drain current		–	180	mA
$-I_{DM}$	peak drain current		–	720	mA
P_{tot}	total power dissipation	up to T_{amb} = 25 °C (note 1)	–	1.5	W
T_{stg}	storage temperature range		–65	150	°C
T_j	junction temperature		–	150	°C

THERMAL RESISTANCE

SYMBOL	PARAMETER	THERMAL RESISTANCE
$R_{th\ j\text{-}a}$	from junction to ambient (note 1)	83.3 K/W

Note

1. Transistor mounted on an epoxy printed circuit board, 40 x 40 x 1.5 mm, mounting pad for the drain tab minimum 6 cm².

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CHARACTERISTICS

T_j = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$-V_{(BR)DSS}$	drain-source breakdown voltage	$-I_D$ = 10 µA; V_{GS} = 0	240	–	–	V
$-I_{DSS}$	drain-source leakage current	$-V_{DS}$ = 200 V; V_{GS} = 0	–	–	1	µA
$\pm I_{GSS}$	gate-source leakage current	$\pm V_{GS}$ = 20 V; V_{DS} = 0	–	–	100	nA
$-V_{GS(th)}$	gate-source threshold voltage	$-I_D$ = 1 mA; V_{GS} = V_{DS}	0.8	–	2	V
$-V_{GS}$	gate-source voltage	$-I_D$ = 50 mA; $-V_{DS}$ = 5 V	0.8	–	2.8	V
$R_{DS(on)}$	drain-source on-resistance	$-I_D$ = 180 mA; $-V_{GS}$ = 10 V	–	10	20	Ω
		$-I_D$ = 100 mA; $-V_{GS}$ = 5 V	–	–	18	Ω
		$-I_D$ = 25 mA; $-V_{GS}$ = 2.8 V	–	–	20	Ω
$\|Y_{fs}\|$	transfer admittance	$-I_D$ = 180 mA; $-V_{DS}$ = 25 V	100	200	–	mS
C_{iss}	input capacitance	$-V_{DS}$ = 25 V; V_{GS} = 0; f = 1 MHz	–	65	90	pF
C_{oss}	output capacitance	$-V_{DS}$ = 25 V; V_{GS} = 0; f = 1 MHz	–	20	30	pF
C_{rss}	feedback capacitance	$-V_{DS}$ = 25 V; V_{GS} = 0; f = 1 MHz	–	6	15	pF
Switching times (see Figs 3 and 4)						
t_{on}	turn-on time	$-I_D$ = 250 mA; $-V_{DD}$ = 50 V; $-V_{GS}$ = 0 to 10 V	–	5	10	ns
t_{off}	turn-off time	$-I_D$ = 250 mA; $-V_{DD}$ = 50 V; $-V_{GS}$ = 0 to 10 V	–	20	30	ns

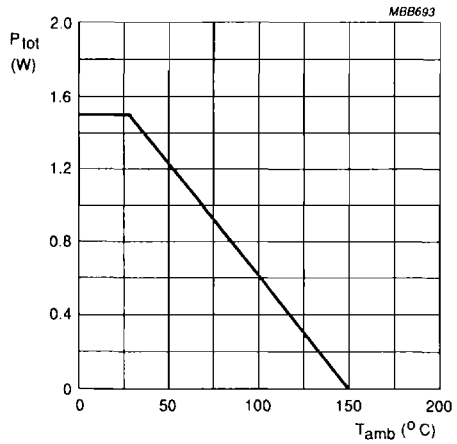
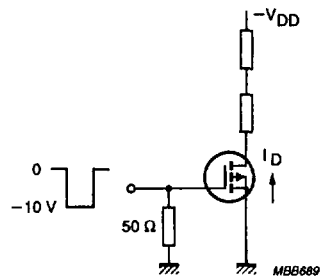


Fig.2 Power derating curve.



$-V_{DD}$ = 50 V.

Fig.3 Switching times test circuit.

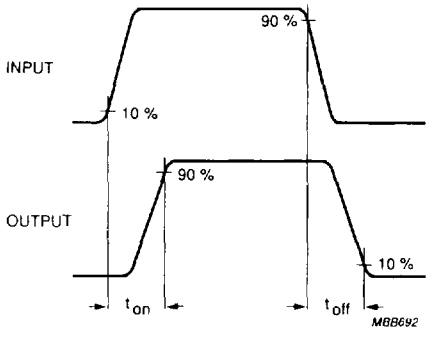


Fig.4 Input and output waveforms.